



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 9257**
Tetsuji TOGAWA et al. : Attorney Docket No. 2005_0993A
Serial No. 10/539,245 : Group Art Unit 3723
Filed March 29, 2006 : Examiner Maurina T. Rachuba
SUBSTRATE HOLDING MECHANISM, : **Mail Stop: AMENDMENT**
SUBSTRATE POLISHING APPARATUS
AND SUBSTRATE POLISHING METHOD

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action of September 25, 2007, the period for response to which having been extended by one month to January 25, 2008, kindly amend the above-referenced U.S. patent application as follows: